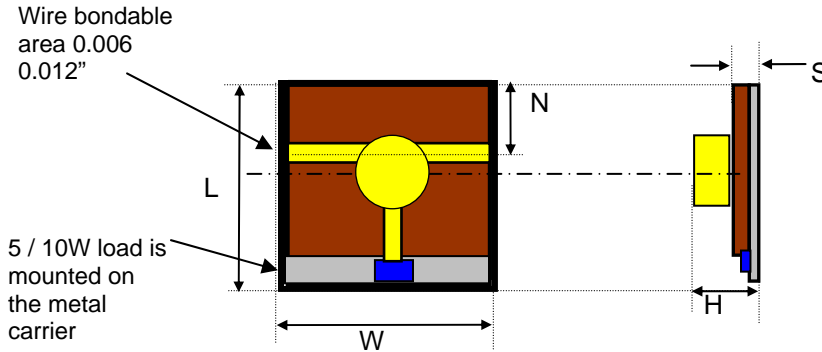


## Isolators: Microstrip Metal Backed RADI/C-FLOW-FHIGH-MSSMH-XW-L/R-e



**Tolerance Table Metric (inch)**

(unless otherwise stated):

Dimensions (w\*I\*h) +/- 0.3 mm, (+/- 0.015")

Dimensions (Microstrip pad, Stripline Tab,

+/- 0.1mm, (+/- 0.04")

**Machined surfaces**

Flatness 0.025/mm, (0.001/ inch)

Bend radius 0.8mm, (0.031" or 1/32")

**Units: Inch (mm)  
Not to scale**

The thin film Microstrip lines are suitable for soldering or thermo-compression gap welding.

Specifications over full operating temperature (-30 to +80 °C)

Storage temperature (-40 to +85°C)

**Direction of RF:**

<b>R</b>	Default	▶
<b>L</b>		◀

Order Examples: **RADI-5.9-7.1-MSSMH-1WR-e**  
**I=ISOLATOR**

I	C	Model#	FREQ	Ins loss dB	Isol dB	VSWR	Pwr Fwd W	Pwr Rev W	Oper. Temp	Customer part #
I		M1	5.915-6.425	0.5	20	1.22:1	5	5	-30 to 80 °C	-073
I		M1	6.425-7.125	0.5	20	1.22:1	5	5	-30 to 80 °C	-074
I		M1	7.11-7.90	0.5	20	1.22:1	5	5	-30 to 80 °C	-075
I		M1	7.725-8.5	0.5	20	1.22:1	5	5	-30 to 80 °C	-076
I		M1	10.5-11.7	0.6	20	1.22:1	5	5	-30 to 80 °C	-077
			all units screened			1.19:1 @ RT				
		M2	5.9-7.1	0.6	16	1.40:1	10	1	-10 to 70 °C	
I		M2	5.9-7.1	0.6	16	1.40:1	10	10	-10 to 70 °C	
I		M2	7.9-8.5	0.5	20	1.35:1	3	1	-30 to 75 °C	
I		M2	7.1-8.5	0.6	16	1.40:1	10	2	-10 to 70 °C	
I		M2	7.1-8.5	0.6	16	1.40:1	10	10	-10 to 70 °C	
I		M3	10.5-11.7	0.6	20	1.22:1	5	5	-30 to 80 °C	-077
			all units screened			1.19:1 @ RT				
I		M4	10.6-11.8	0.6	17	1.30:1	10	10	25 to 85 °C	
I		M4	10.0-10.71	0.6	17	1.30:1	10	1	25 to 85 °C	
I		M5	12.75-13.25	0.7	19	1.30:1	2	2	-30 to 80 °C	
I		M5	14.20-14.50	0.7	19	1.30:1	2	2	-30 to 80 °C	
I		M5	14.40-15.35	0.7	19	1.30:1	2	2	-30 to 80 °C	
I		M6	17.70-19.70	0.7	19	1.30:1	2	2	-30 to 80 °C	
I		M7	9.3-10.0	0.5	20	1.22	5	5	-30 to +85	

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### Dimensions

Model#		W +/-0.003"	L +/-0.003"	H Max	N	X	S	Customer part #	Notes
M1	in	0.470	0.470	0.110	0.235	ns	0.025	094-020081-072-6	Mica Replacements
M1	mm	11.938	11.938	2.79	5.969	ns	0.635		
M2	in	0.470	0.420	0.150	0.210	0.225	0.025		H in 2004
M2	mm	11.938	10.668	3.810	5.334	5.715	0.635		
M3	in	0.330	0.330	0.080	0.145	ns	0.025	094-020081-077	
M3	mm	8.382	8.382	2.032	3.683	ns	0.635		
M4	in	0.330	0.290	0.150	0.145	ns	0.025		
M4	mm	8.382	7.366	3.810	3.683	ns	0.635		
M5	in	0.276	0.276	0.197	0.059	ns	0.020		
M5	mm	7.010	7.010	5.004	1.499	ns	0.508		
M6	in	0.276	0.236	0.158	0.039	ns	0.015		
M6	mm	7.010	5.994	4.013	0.991	ns	0.381		
M7	in	0.470	0.420	0.134	ns	ns	0.045		
M7	mm	11.938	10.668	3.4	ns	ns	1.15		Rfq was 3.0mm max ht

### Notes:

- Line width 0.14mm (typical),
- unit should be mounted with thin smear of non conductive epoxy, with temperature of polymerization close to 80 deg c, but important to leave area around microstrip junctions clear to facilitate grounding.
- Distance from a module cover about 1.0 - 1.5mm without any change in performances and about 0.7mm with minimum changes.
- If soldering keep temperature to 130 deg °C for 3 - 5 minutes Max.
- If non ultrasonic wedge bonding heat the unit to 150°C for 3 minutes max
- Maximum temperature during welding process 350°C for 25mSec
- Curing: survives non operating 120 °C for up to 10 min.// 150 °C for up to 3 min.,